

Vishay Siliconix

N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
100	0.105 at V _{GS} = 10 V	4.6	8.5 nC			

SO-8 S 1 8 D S 2 7 D S 3 6 D Top View

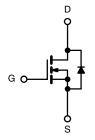
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchET[®] Power MOSFET
- 100 % R_g Tested
- 100 % Avalanche Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

- High Frequency DC/DC Converter
- High Frequency Boost Converter
- LED Backlight for LCD TV



N-Channel MOSFET

Ordering Information: Si4104DY-T1-E3 (Lead (Pb)-free)

Si4104DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	100	V	
Gate-Source Voltage		V_{GS}	± 20	V	
	T _C = 25 °C		4.6		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C	I _D	3.7		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C		3.2 ^{b, c}		
	T _A = 70 °C		2.6 ^{b, c}	^	
Pulsed Drain Current		I _{DM}	15	A	
Continuous Course Ducin Diede Current	T _C = 25 °C	T _C = 25 °C	4.1		
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	2.0 ^{b, c}		
Single Pulse Avalanche Current		I _{AS}	9		
Single Pulse Avalanche Energy L = 0.1 mH		E _{AS}	4	mJ	
	T _C = 25 °C		5.0		
Maximum Power Dissipation	T _C = 70 °C	В	3.2	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{b, c}	VV	
	T _A = 70 °C	1	1.6 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R_{thJA}	38	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	20	25	C/VV	

Notes

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 85 $^{\circ}\text{C/W}.$

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SPECIFICATIONS T _J = 25 °C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static	1				_	ı		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		112		mV/°C		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	ι ₀ = 200 μ. τ		- 8.5				
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2.5		4.5	V		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA		
Zero Gate Voltage Drain Current		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1			
	I _{DSS}	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.085	0.105	Ω		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 5 A		7		S		
Dynamic ^b								
Input Capacitance	C _{iss}			446		pF		
Output Capacitance	C _{oss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		47				
Reverse Transfer Capacitance	C _{rss}			18				
Total Gate Charge	Qg			8.5	13	nC		
Gate-Source Charge	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		3				
Gate-Drain Charge	Q _{gd}			2.5				
Gate Resistance	R_g	f = 1 MHz	0.3	1.3	2.5	Ω		
Turn-On Delay Time	t _{d(on)}			9	18			
Rise Time	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 10 \Omega$		9	18	ns		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		10	20			
Fall Time	t _f			8	16			
Drain-Source Body Diode Characteristic	s							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			4.6			
Pulse Diode Forward Current ^a	I _{SM}				15	A		
Body Diode Voltage	V_{SD}	I _S = 2 A		0.82	1.2	٧		
Body Diode Reverse Recovery Time	t _{rr}			54	80	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		135	200	nC		
Reverse Recovery Fall Time	t _a			48		ns		
Reverse Recovery Rise Time t _b				6				

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

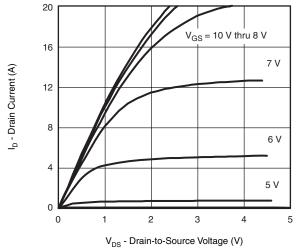
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

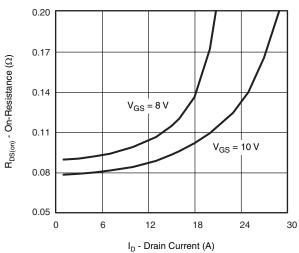


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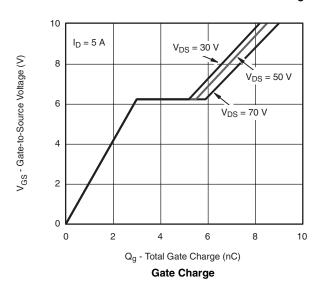
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

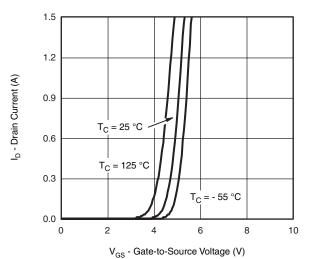


Output Characteristics

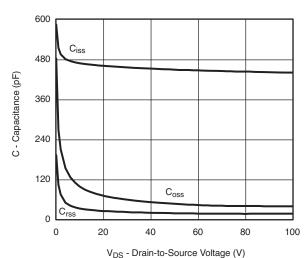


On-Resistance vs. Drain Current and Gate Voltage

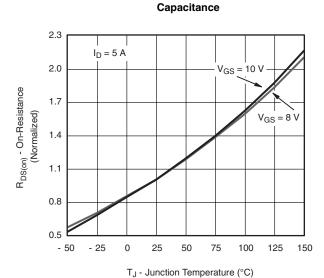




Transfer Characteristics



VDS - Drain-to-Source voitage (



On-Resistance vs. Junction Temperature

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- 0.7

- 1.0

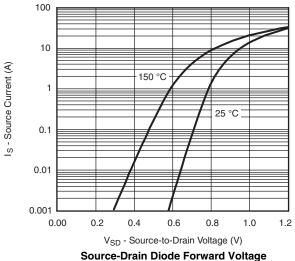
- 50

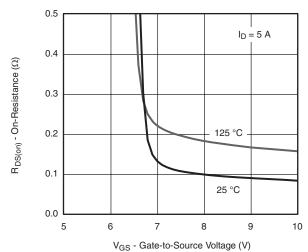
- 25

0

25

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







T_J - Temperature (°C) **Threshold Voltage**

50

75

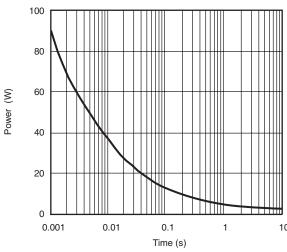
 $I_D = 250 \mu A$

125

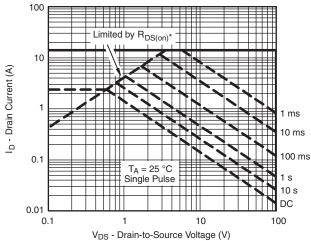
150

100





Single Pulse Power, Junction-to-Ambient



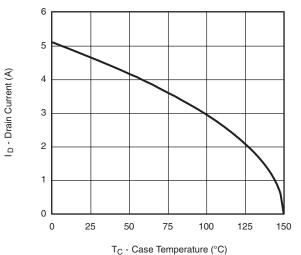
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

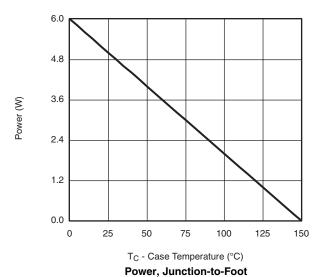


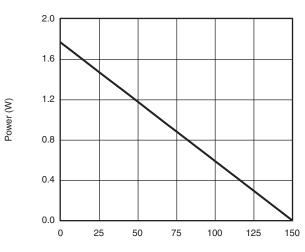
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





T_A - Ambient Temperature (°C)

Power, Junction-to-Ambient

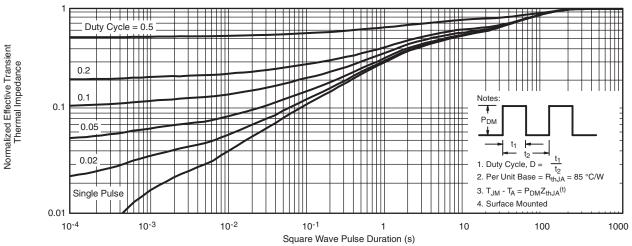
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package

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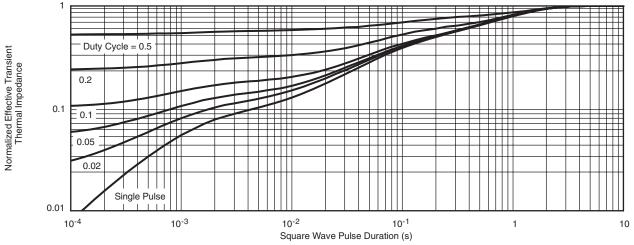
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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